

August 2014

# FDP39N20 / FDPF39N20 N-Channel UniFET<sup>TM</sup> MOSFET 200 V, 39 A, 66 m $\Omega$

### **Features**

- $R_{DS(on)}$  = 66 m $\Omega$  (Max.) @  $V_{GS}$  = 10 V,  $I_D$  = 19.5 A
- Low Gate Charge (Typ. 38 nC)
- Low C<sub>rss</sub> (Typ. 57 pF)
- 100% Avalanche Tested

## **Applications**

- PDP TV
- Lighting
- · Uninterruptible Power Supply
- · AC-DC Power Supply

## Description

UniFET<sup>TM</sup> MOSFET is Fairchild Semiconductor's high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.



## **Absolute Maximum Ratings** T<sub>C</sub> = 25°C unless otherwise noted.

Symbol		Parameter		FDP39N20	FDPF39N20 / FDPF39N20TLDTU	Unit
$V_{DSS}$	Drain-Source Voltage	e		2	V	
I <sub>D</sub>	Drain Current - Continuous ( $T_C = 25^{\circ}C$ ) - Continuous ( $T_C = 100^{\circ}C$ )			39 23.4	39 * 23.4 *	A A
I <sub>DM</sub>	Drain Current	- Pulsed	(Note 1)	156	156 *	Α
V <sub>GSS</sub>	Gate-Source voltage			1	V	
E <sub>AS</sub>	Single Pulsed Avalanche Energy		(Note 2)	860		mJ
I <sub>AR</sub>	Avalanche Current		(Note 1)	39		Α
E <sub>AR</sub>	Repetitive Avalanche Energy		(Note 1)	25.1		mJ
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	4	4.5	V/ns
P <sub>D</sub>	Power Dissipation	(T <sub>C</sub> = 25°C) - Derate Above 25°C		251 2.0	37 0.29	W W/°C
T <sub>J,</sub> T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150		°C	
T <sub>L</sub>	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds			300		

<sup>\*</sup> Drain current limited by maximum junction temperature.

## **Thermal Characteristics**

Symbol	Parameter	FDP39N20	FDPF39N20 / FDPF39N20TLDTU	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.5	3.4	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	62.5	C/VV

## **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FDP39N20	FDP39N20	TO-220	Tube	N/A	N/A	50 units
FDPF39N20	FDPF39N20	TO-220F	Tube	N/A	N/A	50 units
FDPF39N20TLDTU	FDPF39N20T	TO-220F (L-formed)	Tube	N/A	N/A	50 units

## $\textbf{Electrical Characteristics} \quad \textbf{T}_{C} = 25^{\circ} \text{C unless otherwise noted}.$

Symbol	Parameter Conditions		Min.	Тур.	Max.	Unit
Off Charac	cteristics			•	•	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	200			V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C		0.2		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V V <sub>DS</sub> = 160 V, T <sub>C</sub> = 125°C			1 10	μA μA
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -30 V, V <sub>DS</sub> = 0 V			-100	nA
On Charac	teristics			•		
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		5.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 19.5 A	-	0.056	0.066	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 19.5 A		28.5		S
Dynamic C	Characteristics		1		ı	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V,		1640	2130	pF
C <sub>oss</sub>	Output Capacitance	f = 1.0 MHz		400	520	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			57	85	pF
Switching	Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 100 V, I <sub>D</sub> = 39 A,		30	70	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{GS}$ = 10 V, $R_G$ = 25 $\Omega$		160	330	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		/	150	310	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)		150	310	ns
Qg	Total Gate Charge	V <sub>DS</sub> = 160 V, I <sub>D</sub> = 39 A,	/	38	49	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 10 V		11		nC
Q <sub>gd</sub>	Gate-Drain Charge	(Note 4)		16.5		nC
Drain-Sou	rce Diode Characteristics and Maximun	n Ratings		1		
Maximum Continuous Drain-Source Diode Forward Current				39	Α	
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current				156	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 39 A			1.4	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 39 A,		152		ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI <sub>F</sub> /dt =100 A/μs		1.1		μC

#### Notes

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2. L = 0.85 mH, I $_{AS}$  = 39 A, V $_{DD}$  = 50 V, R $_{G}$  = 25  $\Omega$ , starting T $_{J}$  = 25°C.
- 3. I<sub>SD</sub>  $\leq$  39 A, di/dt  $\leq$  200 A/ $\mu$ s, V<sub>DD</sub>  $\leq$  BV<sub>DSS</sub>, starting T<sub>J</sub> = 25°C.
- ${\bf 4.} \ {\bf Essentially \ independent \ of \ operating \ temperature \ typical \ characteristics.}$

## **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

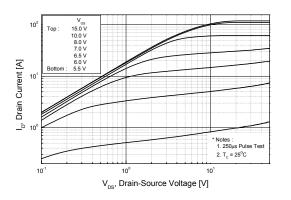


Figure 2. Transfer Characteristics

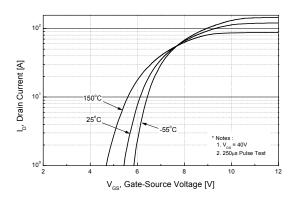
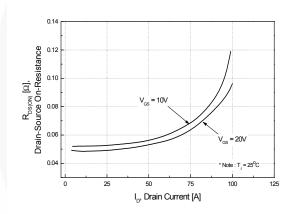


Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage

Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue



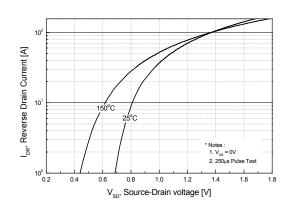


Figure 5. Capacitance Characteristics

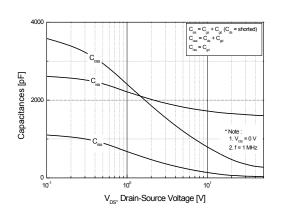
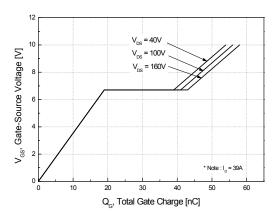


Figure 6. Gate Charge Characteristics



## **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

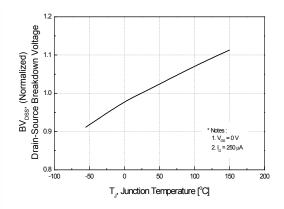


Figure 8. On-Resistance Variation vs. Temperature

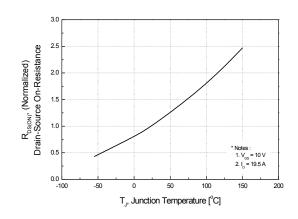


Figure 9-1. Maximum Safe Operating Area - FDP39N20

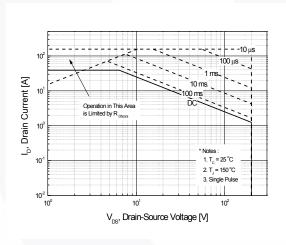


Figure 9-2. Maximum Safe Operating Area - FDPF39N20

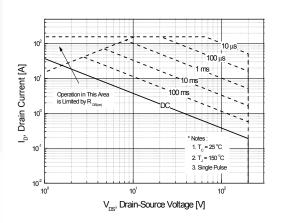
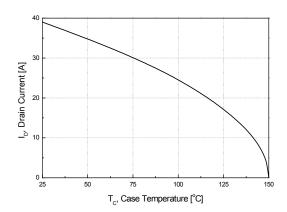


Figure 10. Maximum Drain Current vs. Case Temperature



## **Typical Performance Characteristics** (Continued)

Figure 11-1. Transient Thermal Response Curve - FDP39N20

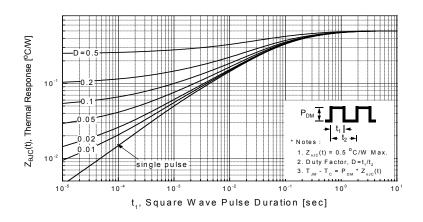
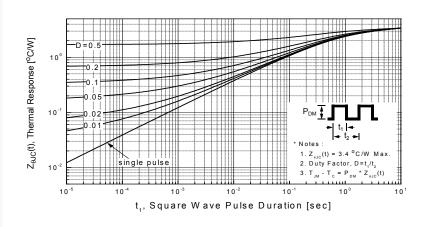


Figure 11-2. Transient Thermal Response Curve - FDPF39N20



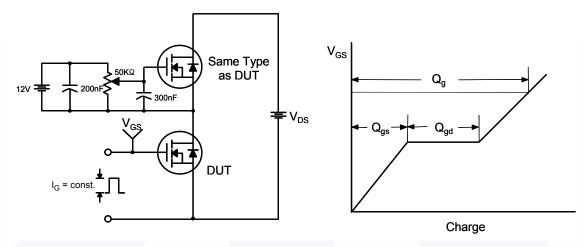


Figure 12. Gate Charge Test Circuit & Waveform

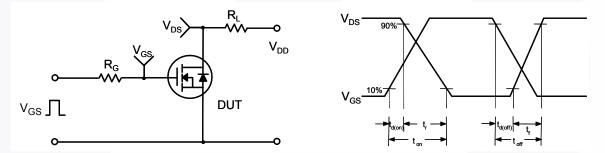


Figure 13. Resistive Switching Test Circuit & Waveforms

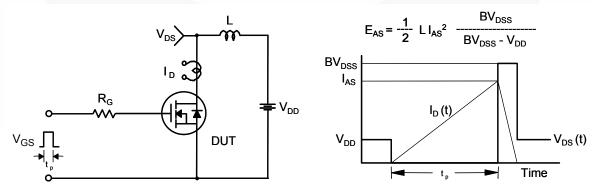


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

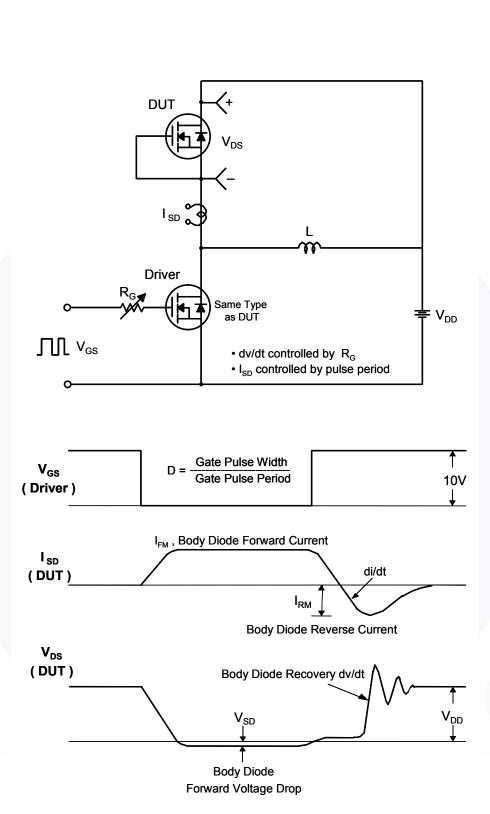


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

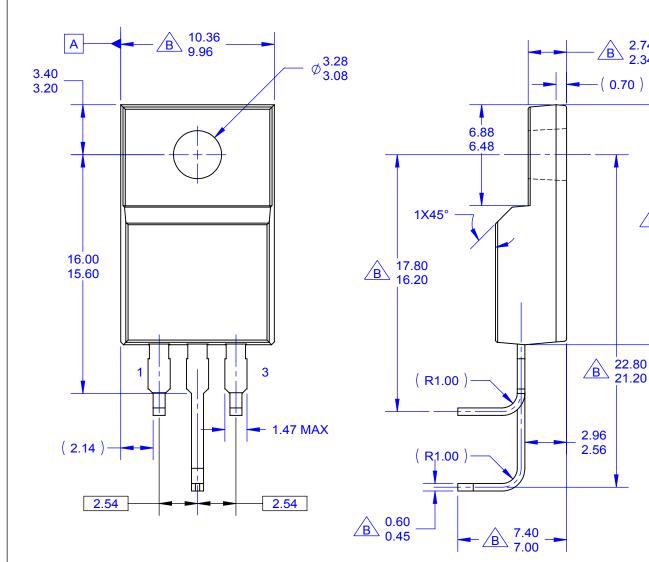
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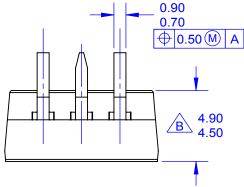
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## **NOTES**:

A. EXCEPT WHERE NOTED CONFORMS TO EIAJ SC91A.

B DOES NOT COMPLY EIAJ STD VALUE.

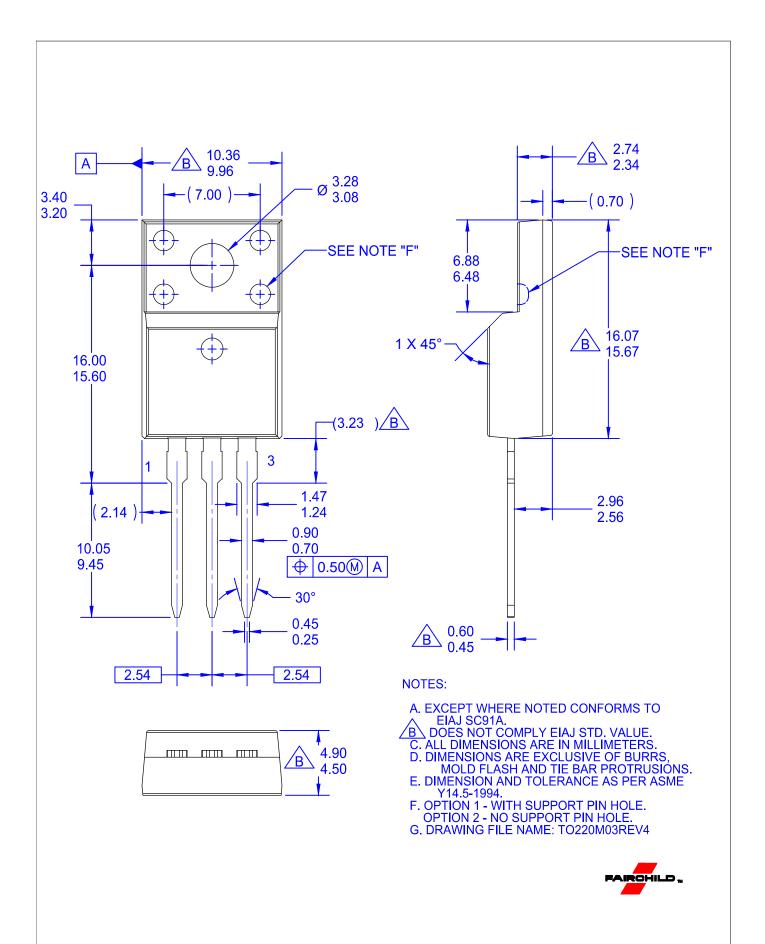
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